

Title (en)

SEMICONDUCTOR CHIP STACK AND METHOD FOR PASSIVATING A SEMICONDUCTOR CHIP STACK

Title (de)

HALBLEITERCHIPSTAPEL UND VERFAHREN ZUR PASSIVIERUNG EINES HALBLEITERCHIPSTAPELS

Title (fr)

EMPILEMENT DE PUCES A SEMICONDUCTEUR ET PROCEDE DE PASSIVATION D'UN EMPILEMENT DE PUCES A SEMICONDUCTEUR

Publication

**EP 1581965 A2 20051005 (DE)**

Application

**EP 03788833 A 20031202**

Priority

- DE 0303961 W 20031202
- DE 10300711 A 20030110

Abstract (en)

[origin: WO2004064139A2] The invention relates to a semiconductor chip stack, wherein an intermediate gap between the semiconductor chips (1,2) is filled at least along the edge of the top side of the top chip (2) by a spacer (7) made of a photostructurable polymer, a photo-resist of a casting compound or an adhesive and thus outwardly sealed. Terminal contact surfaces (5) for bond wires (6) or other external connections are kept free from the material of said spacer on the top side of the bottom chip (1).

IPC 1-7

**H01L 21/56**; H01L 25/065; H01L 21/98

IPC 8 full level

**H01L 21/56** (2006.01); **H01L 25/065** (2006.01)

CPC (source: EP US)

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C-Set (source: EP US)

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Citation (search report)

See references of WO 2004064139A2

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DOCDB simple family (publication)

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